

# Hyperfast Rectifier, 2 A FRED Pt®



SMA (DO-214AC)



## FEATURES

- Hyperfast recovery time, reduced  $Q_{rr}$ , and soft recovery
- 175 °C maximum operating junction temperature
- Specified for output and snubber operation
- Low forward voltage drop
- Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified, meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

## DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers specifically designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness, and reliability characteristics.

These devices are intended for use in snubber, boost, lighting, piezo injection, as high frequency rectifiers, and freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce power dissipation in the switching element.

## PRIMARY CHARACTERISTICS

|                       |                |
|-----------------------|----------------|
| $I_{F(AV)}$           | 2 A            |
| $V_R$                 | 100 V          |
| $V_F$ at $I_F$        | 0.75 V         |
| $t_{rr}$              | 25 ns          |
| $T_J$ max.            | 175 °C         |
| Package               | SMA (DO-214AC) |
| Circuit configuration | Single         |

## ABSOLUTE MAXIMUM RATINGS

| PARAMETER                                   | SYMBOL         | TEST CONDITIONS                  | VALUES      | UNITS |
|---------------------------------------------|----------------|----------------------------------|-------------|-------|
| Peak repetitive reverse voltage             | $V_{RRM}$      |                                  | 100         | V     |
| Average rectified forward current           | $I_{F(AV)}$    | $T_{Sp} = 138$ °C                | 2           | A     |
| Non-repetitive peak surge current           | $I_{FSM}$      | $T_J = 25$ °C, 6 ms square pulse | 50          |       |
| Operating junction and storage temperatures | $T_J, T_{Stg}$ |                                  | -55 to +175 | °C    |

## ELECTRICAL SPECIFICATIONS ( $T_J = 25$ °C unless otherwise specified)

| PARAMETER                           | SYMBOL        | TEST CONDITIONS                   | MIN. | TYP. | MAX. | UNITS   |
|-------------------------------------|---------------|-----------------------------------|------|------|------|---------|
| Breakdown voltage, blocking voltage | $V_{BR}, V_R$ | $I_R = 100$ $\mu$ A               | 100  | -    | -    | V       |
| Forward voltage, per diode          | $V_F$         | $I_F = 2$ A                       | -    | 0.88 | 0.95 |         |
|                                     |               | $I_F = 2$ A, $T_J = 125$ °C       | -    | 0.75 | 0.82 |         |
| Reverse leakage current, per diode  | $I_R$         | $V_R = V_R$ rated                 | -    | -    | 2    | $\mu$ A |
|                                     |               | $T_J = 125$ °C, $V_R = V_R$ rated | -    | 0.6  | 8    |         |
| Junction capacitance                | $C_T$         | $V_R = 100$ V                     | -    | 8.5  | -    | pF      |

| <b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified) |           |                                                                                |      |      |      |       |
|----------------------------------------------------------------------------------------------------------|-----------|--------------------------------------------------------------------------------|------|------|------|-------|
| PARAMETER                                                                                                | SYMBOL    | TEST CONDITIONS                                                                | MIN. | TYP. | MAX. | UNITS |
| Reverse recovery time                                                                                    | $t_{rr}$  | $I_F = 1\text{ A}$ , $dI_F/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$ | -    | 24   | -    | ns    |
|                                                                                                          |           | $I_F = 0.5\text{ A}$ , $I_R = 1\text{ A}$ , $I_{rr} = 0.25\text{ A}$           | -    | -    | 25   |       |
|                                                                                                          |           | $T_J = 25\text{ }^{\circ}\text{C}$                                             | -    | 16   | -    |       |
|                                                                                                          |           | $T_J = 125\text{ }^{\circ}\text{C}$                                            | -    | 22   | -    |       |
| Peak recovery current                                                                                    | $I_{RRM}$ | $T_J = 25\text{ }^{\circ}\text{C}$                                             | -    | 2    | -    | A     |
|                                                                                                          |           | $T_J = 125\text{ }^{\circ}\text{C}$                                            | -    | 3    | -    |       |
| Reverse recovery charge                                                                                  | $Q_{rr}$  | $T_J = 25\text{ }^{\circ}\text{C}$                                             | -    | 16   | -    | nC    |
|                                                                                                          |           | $T_J = 125\text{ }^{\circ}\text{C}$                                            | -    | 30   | -    |       |

| <b>THERMAL - MECHANICAL SPECIFICATIONS</b>     |                |                                                       |       |      |      |                             |
|------------------------------------------------|----------------|-------------------------------------------------------|-------|------|------|-----------------------------|
| PARAMETER                                      | SYMBOL         | TEST CONDITIONS                                       | MIN.  | TYP. | MAX. | UNITS                       |
| Maximum junction and storage temperature range | $T_J, T_{Stg}$ |                                                       | -55   | -    | 175  | $^{\circ}\text{C}$          |
| Thermal resistance, junction to case           | $R_{thJC}$     | Device mounted on PCB with 2 x 3.5 mm soldering lands | -     | 11   | 21   | $^{\circ}\text{C}/\text{W}$ |
| Approximate weight                             |                |                                                       | 0.07  |      |      | g                           |
|                                                |                |                                                       | 0.002 |      |      | oz.                         |
| Marking device                                 |                | Case style SMA (DO-214AC)                             | 2H1   |      |      |                             |

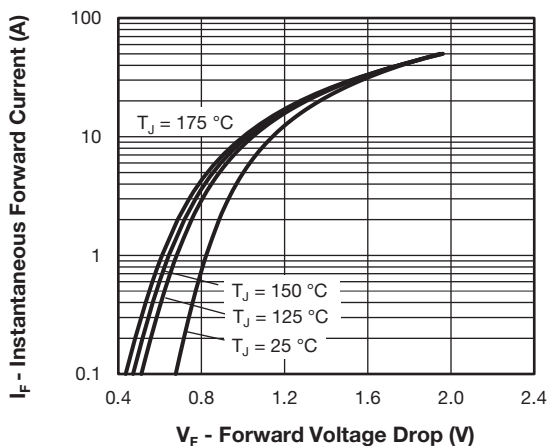


Fig. 1 - Typical Forward Voltage Drop Characteristics

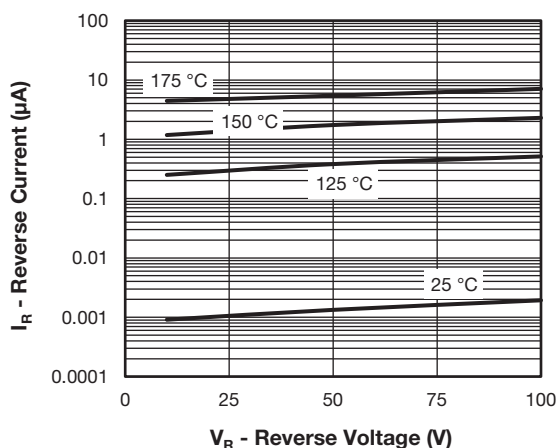


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

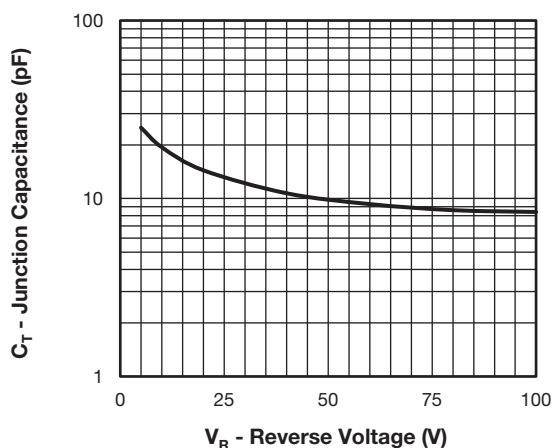


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

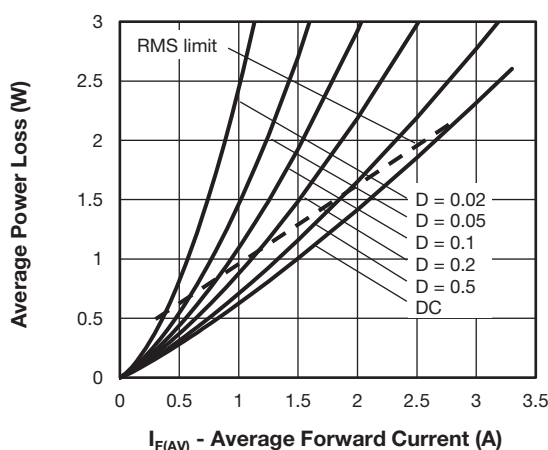


Fig. 5 - Forward Power Loss Characteristics

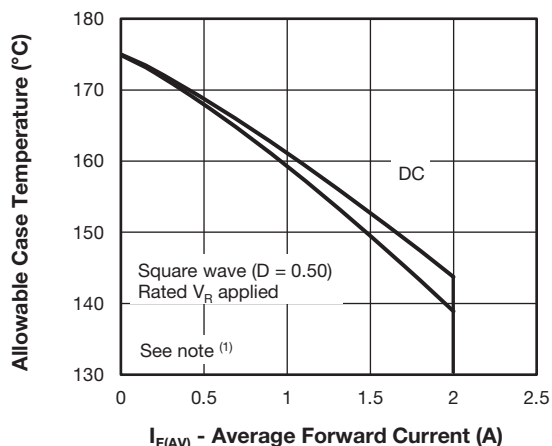


Fig. 4 - Maximum Allowable Case Temperature vs. Average Forward Current

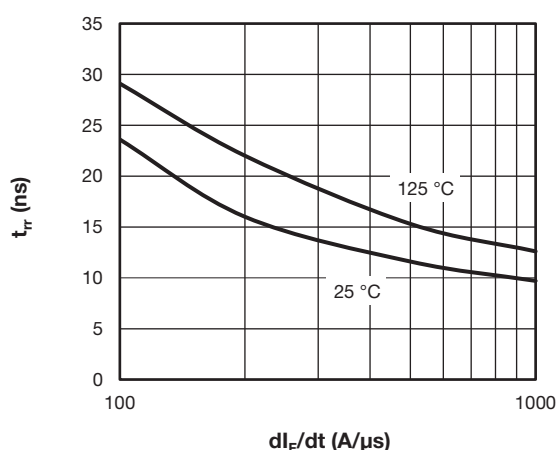


Fig. 6 - Typical Reverse Recovery Time vs.  $dI_F/dt$

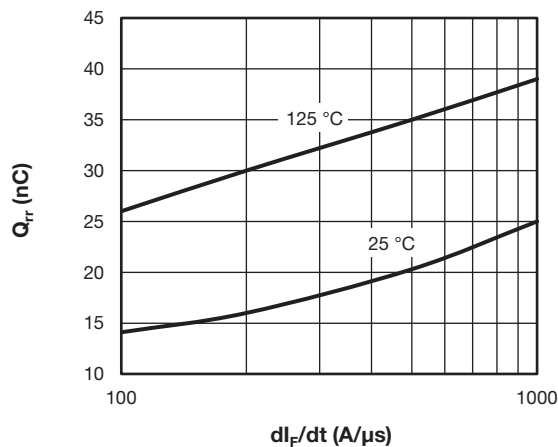


Fig. 7 - Typical Stored Charge vs.  $dI_F/dt$

#### Note

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;  
 $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 5);  
 $P_{dREV}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = rated  $V_R$

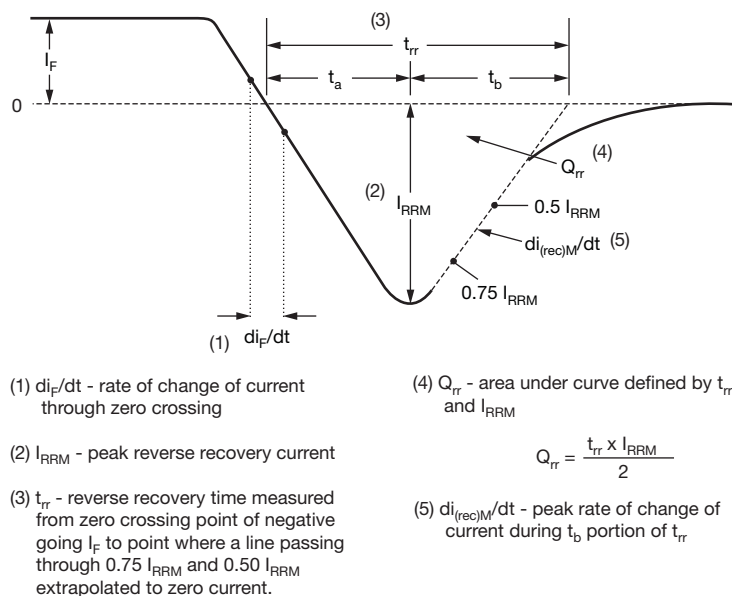


Fig. 8 - Reverse Recovery Waveform and Definitions

## ORDERING INFORMATION TABLE

| Device code | VS- | 2 | E | M | H | 01 | H | M3 |
|-------------|-----|---|---|---|---|----|---|----|
|             | 1   | 2 | 3 | 4 | 5 | 6  | 7 | 8  |

- 1** - Vishay Semiconductors product
- 2** - Current rating (2 = 2 A)
- 3** - Circuit configuration:  
E = single diode
- 4** - M = SMA package
- 5** - Process type,  
H = hyperfast recovery
- 6** - Voltage code (01 = 100 V)
- 7** - H = AEC-Q101 qualified
- 8** - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

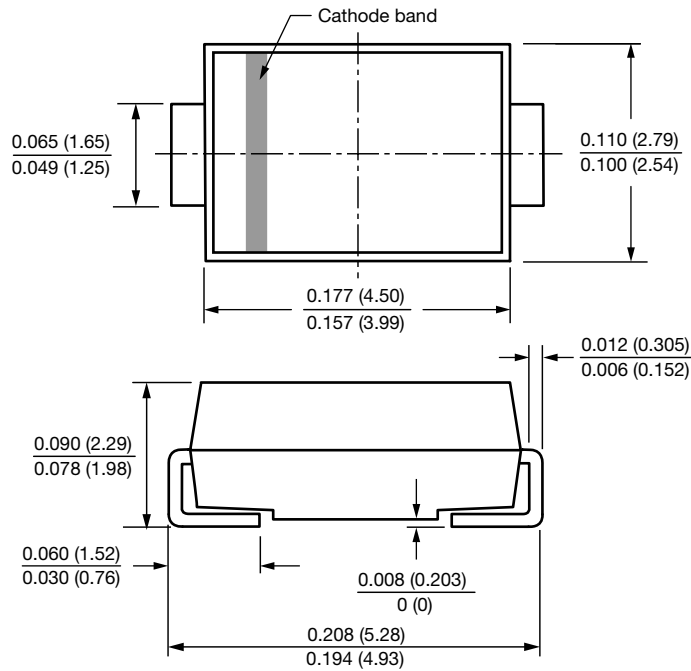
| ORDERING INFORMATION (Example) |                   |                        |                                    |
|--------------------------------|-------------------|------------------------|------------------------------------|
| PREFERRED P/N                  | QUANTITY PER REEL | MINIMUM ORDER QUANTITY | PACKAGING DESCRIPTION              |
| VS-2EMH01HM3/5AT               | 7500              | 7500                   | 13" diameter plastic tape and reel |

| LINKS TO RELATED DOCUMENTS |                                                                        |
|----------------------------|------------------------------------------------------------------------|
| Dimensions                 | <a href="http://www.vishay.com/doc?95400">www.vishay.com/doc?95400</a> |
| Part marking information   | <a href="http://www.vishay.com/doc?95472">www.vishay.com/doc?95472</a> |
| Packaging information      | <a href="http://www.vishay.com/doc?95404">www.vishay.com/doc?95404</a> |
| SPIICE model               | <a href="http://www.vishay.com/doc?96376">www.vishay.com/doc?96376</a> |

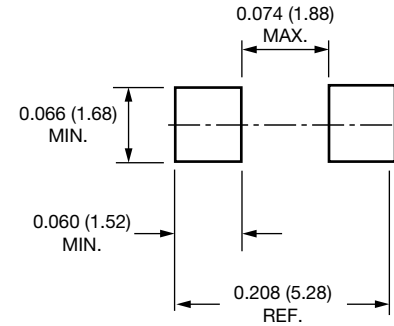
## SMA

**DIMENSIONS** in inches (millimeters)

**DO-214AC (SMA)**



**Mounting Pad Layout**





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